CSD23381F4 12-V P-Channel FemtoFET™ MOSFET

1 Features

- Ultra-low on-resistance
- Ultra-low Q_g and Q_{gd}
- High operating drain current
- Ultra-small footprint (0402 case size)
  - 1.0 mm × 0.6 mm
- Ultra-low profile
  - Maximum height: 0.36 mm
- Integrated ESD protection diode
  - Rated > 4-kV HBM
  - Rated > 2-kV CDM
- Lead and halogen free
- RoHS compliant

2 Applications

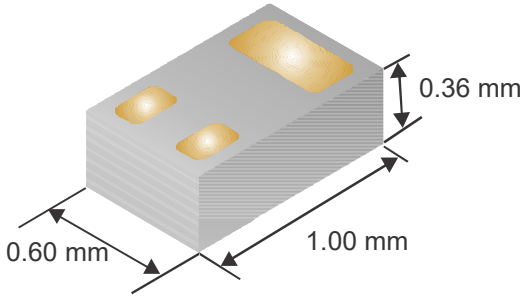
- Optimized for load switch applications
- Optimized for general purpose switching applications
- Battery applications
- Handheld and mobile applications

3 Description

This 150 mΩ, 12 V P-Channel FemtoFET™ MOSFET is designed and optimized to minimize the footprint in many handheld and mobile applications. This technology is capable of replacing standard small signal MOSFETs while providing at least a 60% reduction in footprint size.

Product Summary

T_A = 25°C		TYPICAL VALUE		UNIT
V_{DS}	Drain-to-source voltage	–12		V
Q_g	Gate charge total (–4.5 V)	1140		pC
Q_{gd}	Gate charge gate-to-drain	190		pC
$R_{DS(on)}$	Drain-to-source on-resistance	V_{GS} = –1.8 V	480	mΩ
		V_{GS} = –2.5 V	250	mΩ
		V_{GS} = –4.5 V	150	mΩ



Typical Device Dimensions

Product Summary (continued)

T_A = 25°C		TYPICAL VALUE	UNIT
$V_{GS(th)}$	Threshold voltage	–0.95	V

Ordering Information

Device(1)	Qty	Media	Package	Ship
CSD23381F4	3000	7-inch reel	Femto(0402) 1.0-mm × 0.6-mm Land Grid Array (LGA)	Tape and reel
CSD23381F4T	250			

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

T_A = 25°C		VALUE	UNIT
V_{DS}	Drain-to-source voltage	–12	V
V_{GS}	Gate-to-source voltage	–8	V
I_D	Continuous drain current(1)	–2.3	A
I_{DM}	Pulsed drain current(2)	–9	A
I_G	Continuous gate clamp current	–35	mA
	Pulsed gate clamp current(2)	–350	
P_D	Power dissipation(1)	500	mW
$V_{(ESD)}$	Human body model (HBM)	4	kV
	Charged device model (CDM)	2	kV
T_J, T_{stg}	Operating junction and storage temperature range	–55 to 150	°C

(1) Typical $R_{\theta JA}$ = 85°C/W on 1-inch² (6.45 cm²), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52 mm) thick FR4 PCB.

(2) Pulse duration ≤ 300 µs, duty cycle ≤ 2%

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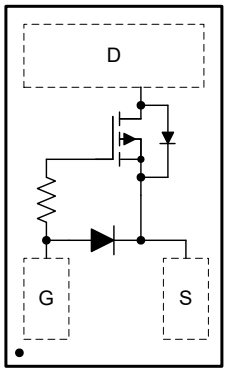

Top View

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4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision F (October 2021) to Revision G (January 2022)	Page
• Changed Maximum height from "0.35 mm" to "0.36 mm" in *Features*	1
• Changed height dimension from "0.35 mm" to "0.36 mm" in *Typical Device Dimensions*	1
• Changed maximum height dimension from "0.35 mm" to "0.36 mm" in *Mechanical Dimensions*	7

Changes from Revision E (May 2015) to Revision F (October 2021)	Page
• Added footnote with link to support document	8

Changes from Revision D (September 2014) to Revision E (May 2015)	Page
• Corrected typo for I_{DSS} Test Condition	3
• Corrected typo for I_{GSS} Test Condition	3

5 Specifications

5.1 Electrical Characteristics

(T_A = 25°C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV_{DSS}	Drain-to-Source Voltage	V_{GS} = 0 V, I_{DS} = –250 µA	–12			V
I_{DSS}	Drain-to-Source Leakage Current	V_{GS} = 0 V, V_{DS} = –9.6 V			–100	nA
I_{GSS}	Gate-to-Source Leakage Current	V_{DS} = 0 V, V_{GS} = –8 V			–50	nA
$V_{GS(th)}$	Gate-to-Source Threshold Voltage	V_{DS} = V_{GS}, I_{DS} = –250 µA	–0.7	–0.95	–1.20	V
$R_{DS(on)}$	Drain-to-Source On-Resistance	V_{GS} = –1.8 V, I_{DS} = –0.1 A		480	970	mΩ
		V_{GS} = –2.5 V, I_{DS} = –0.5 A		250	300	mΩ
		V_{GS} = –4.5 V, I_{DS} = –0.5 A		150	175	mΩ
g_{fs}	Transconductance	V_{DS} = –6 V, I_{DS} = –0.5 A		2		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input Capacitance	V_{GS} = 0 V, V_{DS} = –6 V, f = 1 MHz		236		pF
C_{oss}	Output Capacitance			98		pF
C_{rss}	Reverse Transfer Capacitance			6.9		pF
R_G	Series Gate Resistance			20		Ω
Q_g	Gate Charge Total (4.5 V)	V_{DS} = –6 V, I_{DS} = –0.5 A		1140		pC
Q_{gd}	Gate Charge Gate-to-Drain			190		pC
Q_{gs}	Gate Charge Gate-to-Source			300		pC
$Q_{g(th)}$	Gate Charge at V_{th}			145		pC
Q_{oss}	Output Charge	V_{DS} = –6 V, V_{GS} = 0 V		1290		pC
$t_{d(on)}$	Turn On Delay Time	V_{DS} = –6 V, V_{GS} = –4.5 V, I_{DS} = –0.5 A, R_G = 2 Ω		4.5		ns
t_r	Rise Time			3.9		ns
$t_{d(off)}$	Turn Off Delay Time			18		ns
t_f	Fall Time			7		ns
DIODE CHARACTERISTICS						
V_{SD}	Diode Forward Voltage	I_{SD} = –0.5 A, V_{GS} = 0 V		–0.75		V
Q_{rr}	Reverse Recovery Charge	V_{DS}= –10 V, I_F = –0.5 A, di/dt = 100 A/µs		1260		pC
t_{rr}	Reverse Recovery Time			7.9		ns

5.2 Thermal Information

(T_A = 25°C unless otherwise stated)

THERMAL METRIC		TYPICAL VALUES	UNIT
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance(1)	85	°C/W
	Junction-to-Ambient Thermal Resistance(2)	245	

(1) Device mounted on FR4 material with 1-inch^2 (6.45 cm^2), 2-oz. (0.071 mm thick) Cu.
(2) Device mounted on FR4 material with minimum Cu mounting area.

5.3 Typical MOSFET Characteristics

(T_A = 25°C unless otherwise stated)

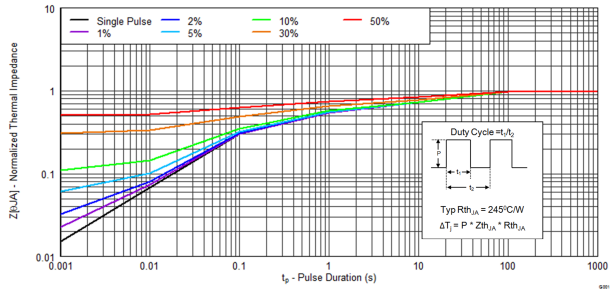


Figure 5-1. Transient Thermal Impedance

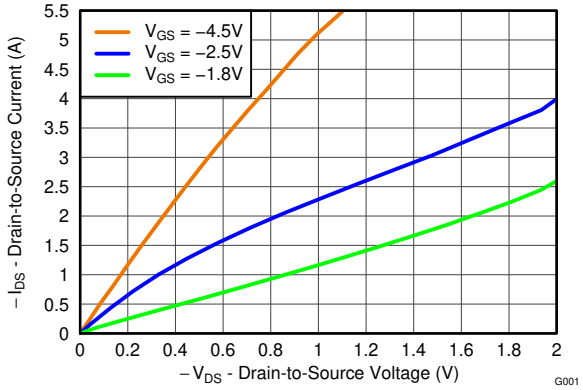


Figure 5-2. Saturation Characteristics

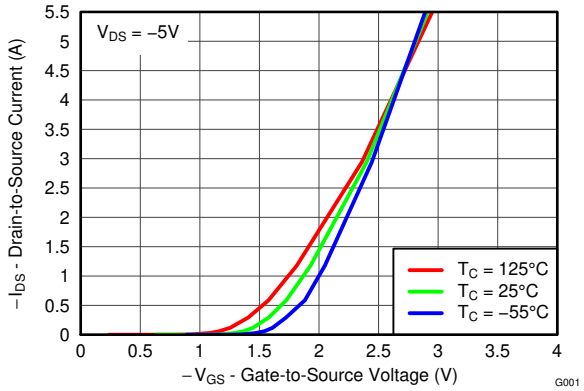


Figure 5-3. Transfer Characteristics

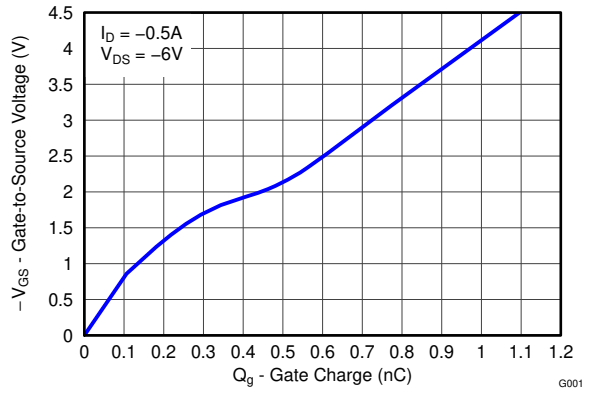


Figure 5-4. Gate Charge

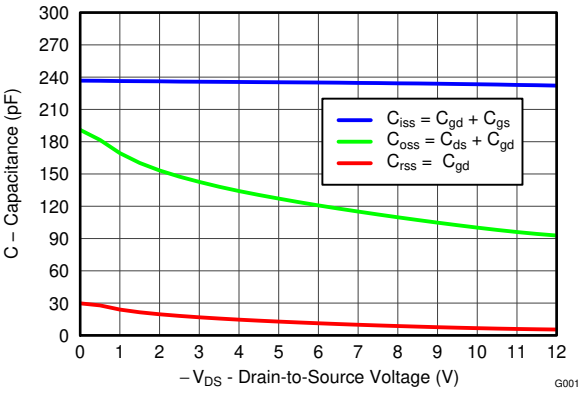


Figure 5-5. Capacitance

5.3 Typical MOSFET Characteristics (continued)

(T_A = 25°C unless otherwise stated)

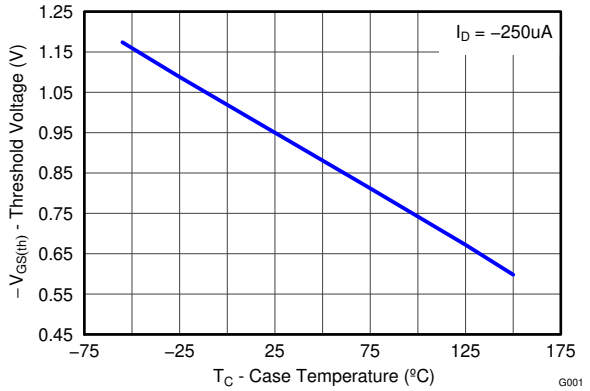


Figure 5-6. Threshold Voltage vs Temperature

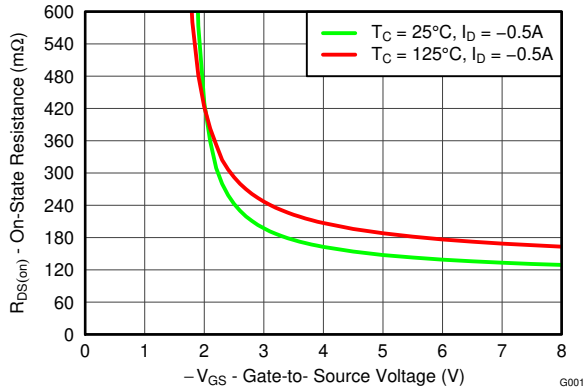


Figure 5-7. On-State Resistance vs Gate-to-Source Voltage

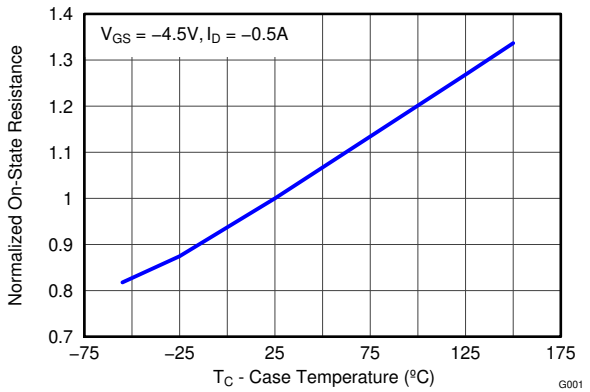


Figure 5-8. Normalized On-State Resistance vs Temperature

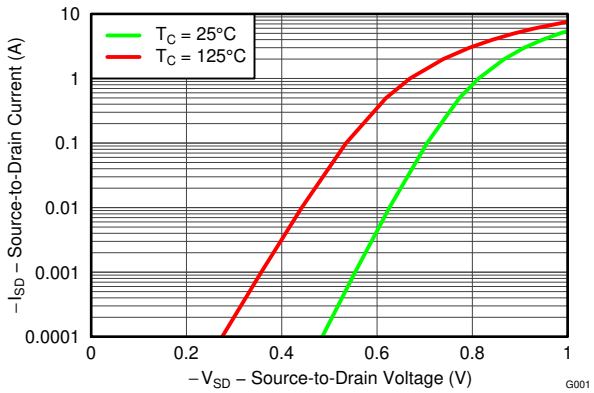


Figure 5-9. Typical Diode Forward Voltage

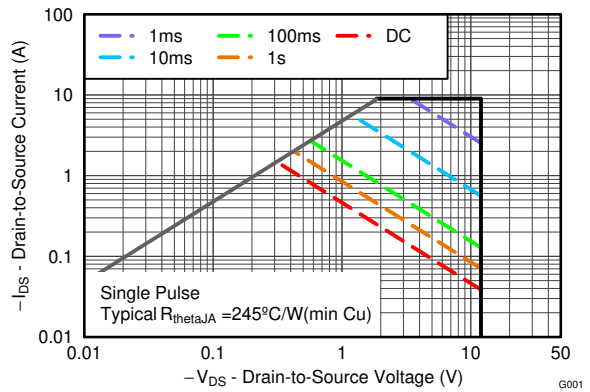


Figure 5-10. Maximum Safe Operating Area

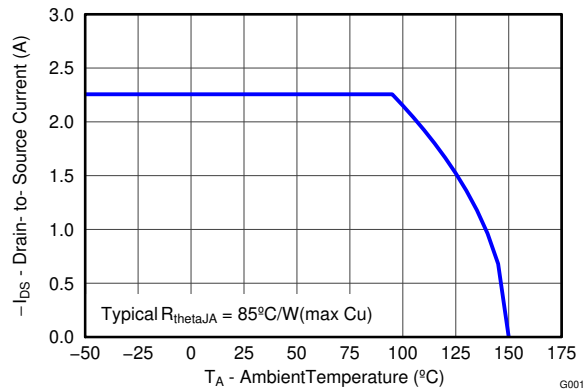


Figure 5-11. Maximum Drain Current vs Temperature

6 Device and Documentation Support

6.1 Trademarks

FemtoFET™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

6.2 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

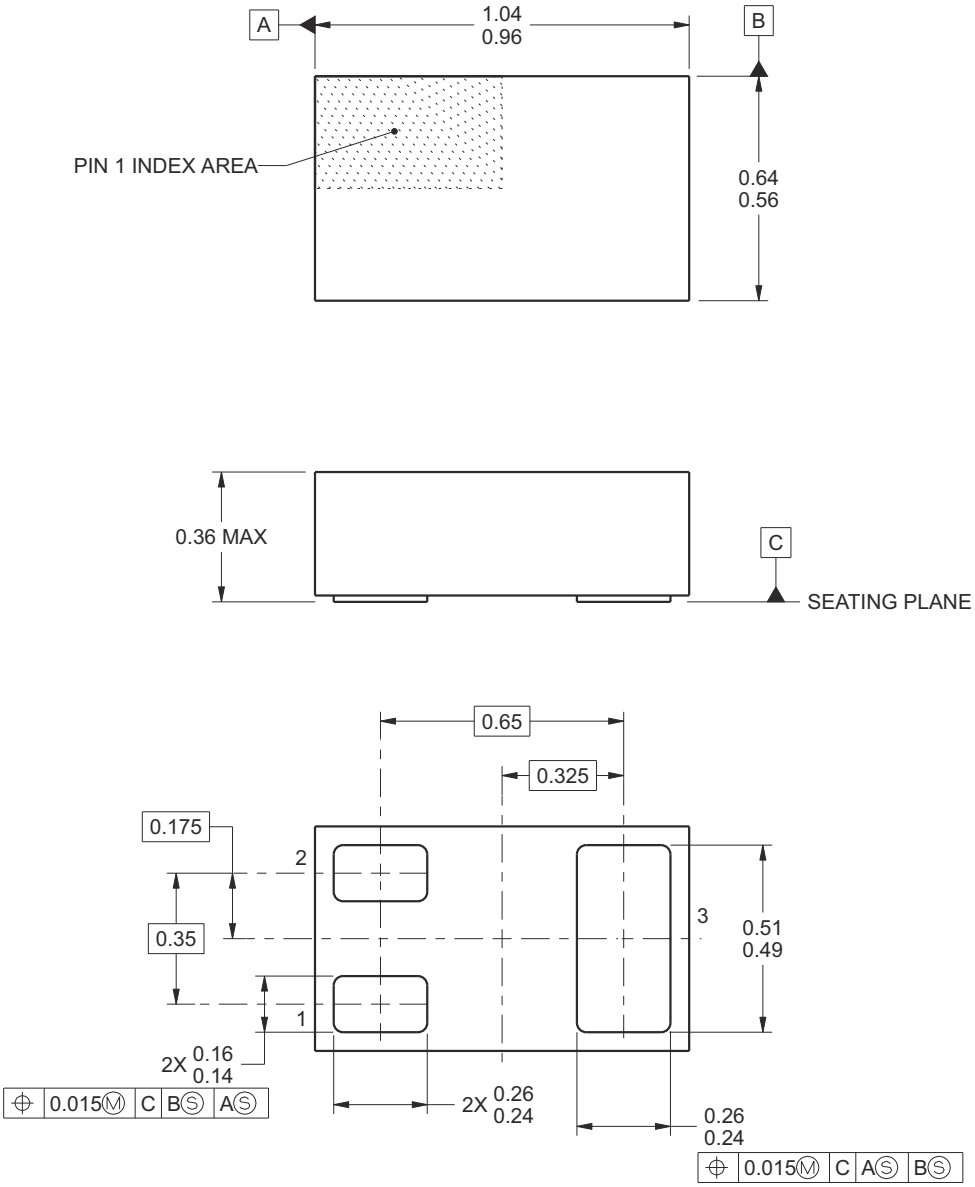
6.3 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

7.1 Mechanical Dimensions

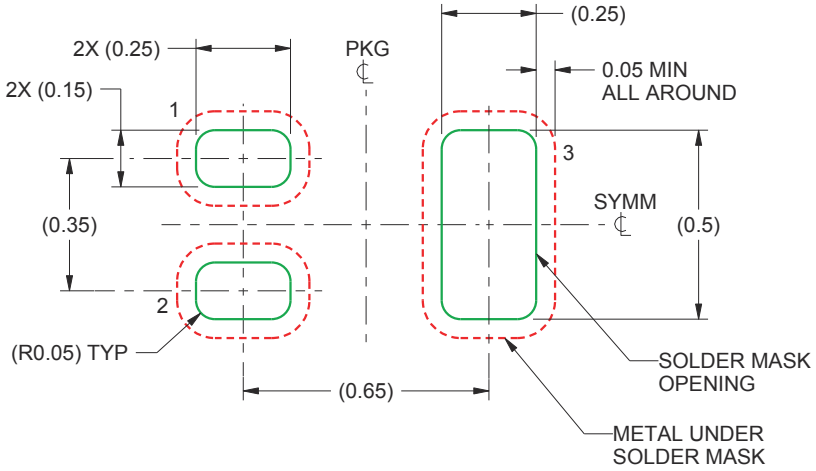


A. All linear dimensions are in millimeters (dimensions and tolerancing per AME T14.5M-1994).
B. This drawing is subject to change without notice.
C. This package is a PB free solder land design.

Pin Configuration

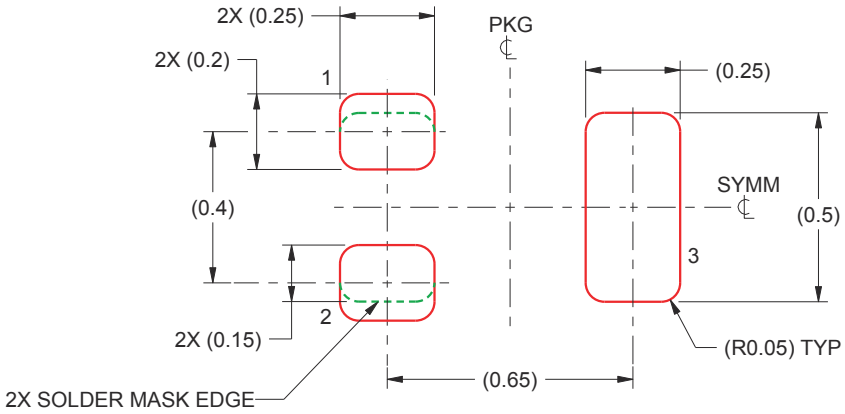
Position	Designation
Pin 1	Gate
Pin 2	Source
Pin 3	Drain

7.2 Recommended Minimum PCB Layout



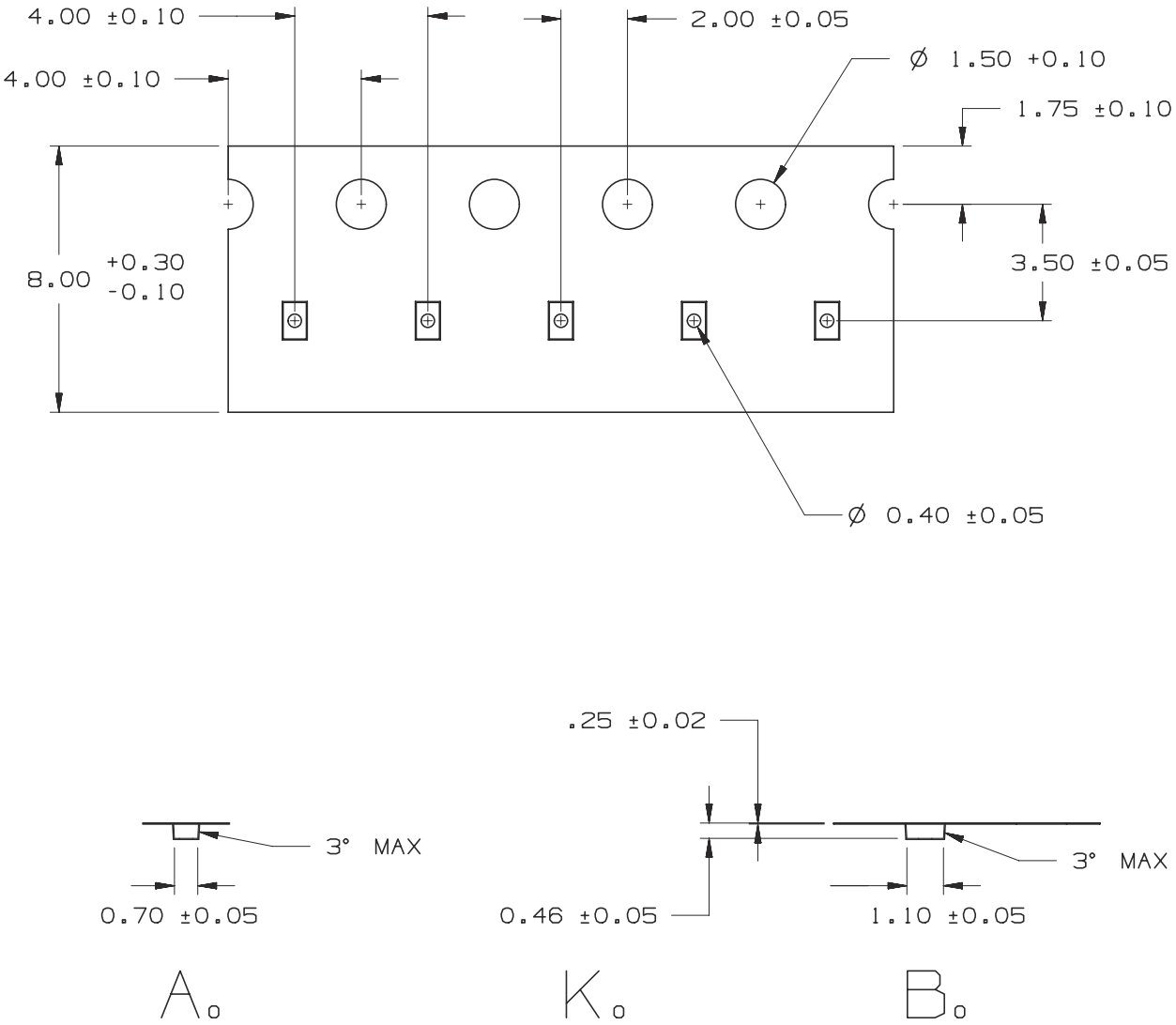
A. All dimensions are in millimeters.
B. For more information, see *FemtoFET Surface Mount Guide* (SLRA003D).

7.3 Recommended Stencil Pattern



A. All dimensions are in millimeters.

7.4 CSD23381F4 Embossed Carrier Tape Dimensions



A. Pin 1 is oriented in the top-right quadrant of the tape enclosure (quadrant 2), closest to the carrier tape sprocket holes.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD23381F4	ACTIVE	PICOSTAR	YJC	3	3000	RoHS & Green	NIAU	Level-1-260C-UNLIM	-55 to 150	DS	Samples
CSD23381F4T	ACTIVE	PICOSTAR	YJC	3	250	RoHS & Green	NIAU	Level-1-260C-UNLIM	-55 to 150	DS	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

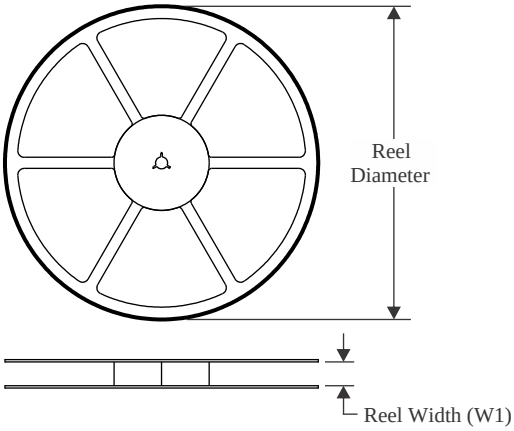
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

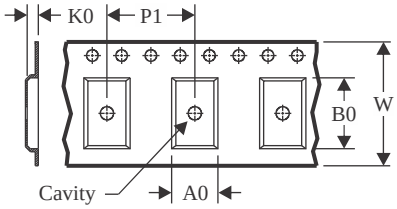
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

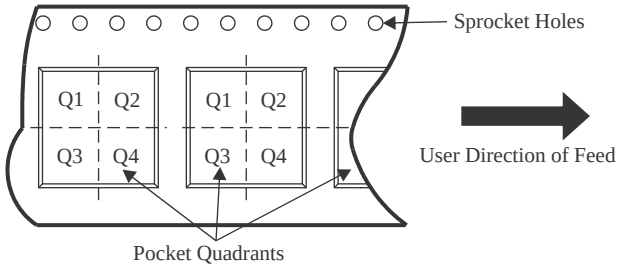


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

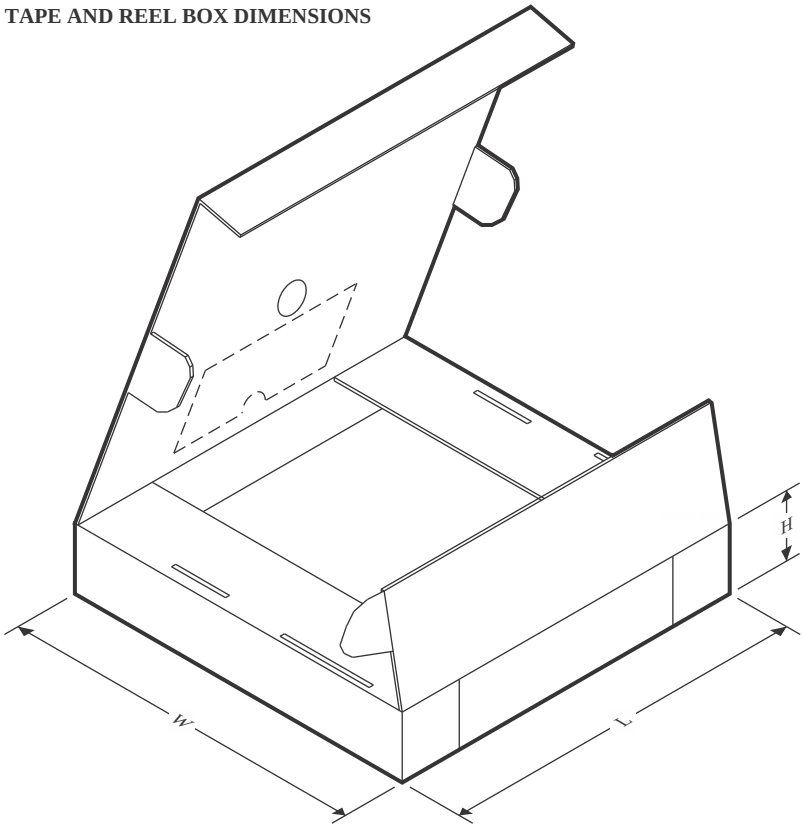
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD23381F4	PICOSTAR	YJC	3	3000	180.0	8.4	0.7	1.1	0.46	4.0	8.0	Q2
CSD23381F4T	PICOSTAR	YJC	3	250	180.0	8.4	0.7	1.1	0.46	4.0	8.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD23381F4	PICOSTAR	YJC	3	3000	182.0	182.0	20.0
CSD23381F4T	PICOSTAR	YJC	3	250	182.0	182.0	20.0

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